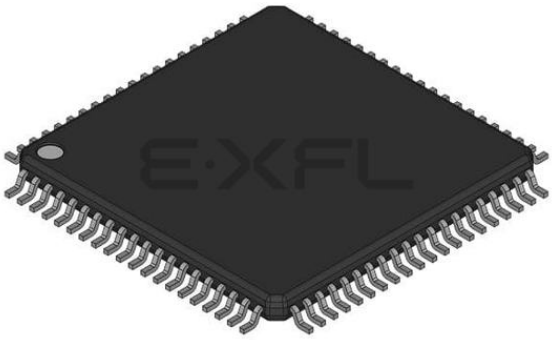

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	Coldfire V2
Core Size	32-Bit Single-Core
Speed	60MHz
Connectivity	CANbus, Ethernet, I²C, SPI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	73
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mcf52231caf60

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  - Based on and includes all existing features of the Freescale TouCAN module
  - Full implementation of the CAN protocol specification version 2.0B
    - Standard Data and Remote Frames (up to 109 bits long)
    - Extended Data and Remote Frames (up to 127 bits long)
    - 0–8 bytes data length
    - Programmable bit rate up to 1 Mbit/sec
  - Flexible Message Buffers (MBs), totalling up to 16 message buffers of 0–8 byte data length each, configurable as Rx or Tx, all supporting standard and extended messages
  - Unused Message Buffer space can be used as general purpose RAM space
  - Listen only mode capability
  - Content-related addressing
  - No read/write semaphores required
  - Three programmable mask registers: global for MBs 0-13, special for MB14, and special for MB15
  - Programmable transmit-first scheme: lowest ID or lowest buffer number
  - Time stamp based on 16-bit free-running timer
  - Global network time, synchronized by a specific message
  - Maskable interrupts
- Three universal asynchronous/synchronous receiver transmitters (UARTs)
  - 16-bit divider for clock generation
  - Interrupt control logic with maskable interrupts
  - DMA support
  - Data formats can be 5, 6, 7 or 8 bits with even, odd or no parity
  - Up to 2 stop bits in 1/16 increments
  - Error-detection capabilities
  - Modem support includes request-to-send (RTS) and clear-to-send (CTS) lines for two UARTs
  - Transmit and receive FIFO buffers
- I^2C module
  - Interchip bus interface for EEPROMs, LCD controllers, A/D converters, and keypads
  - Fully compatible with industry-standard I^2C bus
  - Master and slave modes support multiple masters
  - Automatic interrupt generation with programmable level
- Queued serial peripheral interface (QSPI)
  - Full-duplex, three-wire synchronous transfers
  - Up to four chip selects available
  - Master mode operation only
  - Programmable bit rates up to half the CPU clock frequency
  - Up to 16 pre-programmed transfers
- Fast analog-to-digital converter (ADC)
  - Eight analog input channels
  - 12-bit resolution
  - Minimum 1.125 µs conversion time
  - Simultaneous sampling of two channels for motor control applications
  - Single-scan or continuous operation
  - Optional interrupts on conversion complete, zero crossing (sign change), or under/over low/high limit
  - Unused analog channels can be used as digital I/O

- Four 32-bit DMA timers
  - 17-ns resolution at 60 MHz
  - Programmable sources for clock input, including an external clock option
  - Programmable prescaler
  - Input capture capability with programmable trigger edge on input pin
  - Output compare with programmable mode for the output pin
  - Free run and restart modes
  - Maskable interrupts on input capture or output compare
  - DMA trigger capability on input capture or output compare
- Four-channel general purpose timers
  - 16-bit architecture
  - Programmable prescaler
  - Output pulse widths variable from microseconds to seconds
  - Single 16-bit input pulse accumulator
  - Toggle-on-overflow feature for pulse-width modulator (PWM) generation
  - One dual-mode pulse accumulation channel
- Pulse-width modulation timer
  - Operates as eight channels with 8-bit resolution or four channels with 16-bit resolution
  - Programmable period and duty cycle
  - Programmable enable/disable for each channel
  - Software selectable polarity for each channel
  - Period and duty cycle are double buffered. Change takes effect when the end of the current period is reached (PWM counter reaches zero) or when the channel is disabled.
  - Programmable center or left aligned outputs on individual channels
  - Four clock sources (A, B, SA, and SB) provide for a wide range of frequencies
  - Emergency shutdown
- Real-Time Clock (RTC)
  - Maintains system time-of-day clock
  - Provides stopwatch and alarm interrupt functions
- Two periodic interrupt timers (PITs)
  - 16-bit counter
  - Selectable as free running or count down
- Software watchdog timer
  - 32-bit counter
  - Low power mode support
- Clock Generation Features
  - Crystal input
  - On-chip PLL
  - Provides clock for integrated EPHY
- Dual Interrupt Controllers (INTC0/INTC1)
  - Support for multiple interrupt sources organized as follows:
    - Fully-programmable interrupt sources for each peripheral
    - 7 fixed-level interrupt sources
    - Seven external interrupt signals

pipeline, optimized for 16×16 bit operations, with support for one 32-bit accumulator. Supported operands include 16- and 32-bit signed and unsigned integers, signed fractional operands, and a complete set of instructions to process these data types. The EMAC provides support for execution of DSP operations within the context of a single processor at a minimal hardware cost.

1.2.3 Integrated Debug Module

The ColdFire processor core debug interface is provided to support system debugging in conjunction with low-cost debug and emulator development tools. Through a standard debug interface, access debug information and real-time tracing capability is provided on 112-and 121-lead packages. This allows the processor and system to be debugged at full speed without the need for costly in-circuit emulators.

The on-chip breakpoint resources include a total of nine programmable 32-bit registers: an address and an address mask register, a data and a data mask register, four PC registers, and one PC mask register. These registers can be accessed through the dedicated debug serial communication channel or from the processor's supervisor mode programming model. The breakpoint registers can be configured to generate triggers by combining the address, data, and PC conditions in a variety of single- or dual-level definitions. The trigger event can be programmed to generate a processor halt or initiate a debug interrupt exception. The MCF52235 implements revision B+ of the ColdFire Debug Architecture.

The MCF52235's interrupt servicing options during emulator mode allow real-time critical interrupt service routines to be serviced while processing a debug interrupt event, thereby ensuring that the system continues to operate even during debugging.

To support program trace, the V2 debug module provides processor status (PST[3:0]) and debug data (DDATA[3:0]) ports. These buses and the PSTCLK output provide execution status, captured operand data, and branch target addresses defining processor activity at the CPU's clock rate. The MCF52235 includes a new debug signal, ALLPST. This signal is the logical AND of the processor status (PST[3:0]) signals and is useful for detecting when the processor is in a halted state (PST[3:0] = 1111).

The full debug/trace interface is available only on the 112 and 121-pin packages. However, every product features the dedicated debug serial communication channel (DSI, DSO, DSCLK) and the ALLPST signal.

1.2.4 JTAG

The MCF52235 supports circuit board test strategies based on the Test Technology Committee of IEEE and the Joint Test Action Group (JTAG). The test logic includes a test access port (TAP) consisting of a 16-state controller, an instruction register, and three test registers (a 1-bit bypass register, a 256-bit boundary-scan register, and a 32-bit ID register). The boundary scan register links the device's pins into one shift register. Test logic, implemented using static logic design, is independent of the device system logic.

The MCF52235 implementation can do the following:

- Perform boundary-scan operations to test circuit board electrical continuity
- Sample MCF52235 system pins during operation and transparently shift out the result in the boundary scan register
- Bypass the MCF52235 for a given circuit board test by effectively reducing the boundary-scan register to a single bit
- Disable the output drive to pins during circuit-board testing
- Drive output pins to stable levels

1.2.5 On-Chip Memories

1.2.5.1 SRAM

The dual-ported SRAM module provides a general-purpose 16- or 32-Kbyte memory block that the ColdFire core can access in a single cycle. The location of the memory block can be set to any 16- or 32-Kbyte boundary within the 4-Gbyte address space. This memory is ideal for storing critical code or data structures and for use as the system stack. Because the SRAM

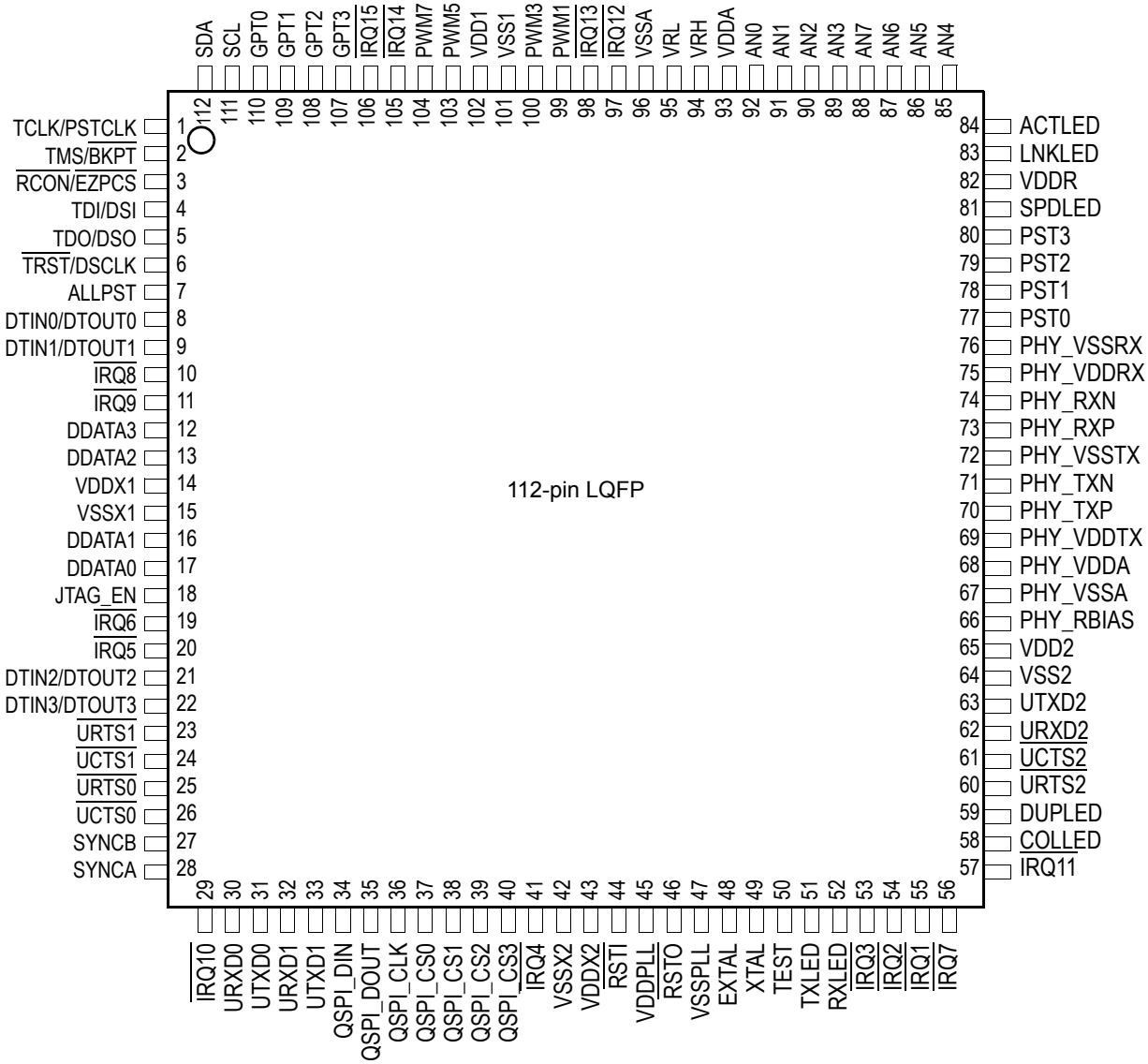


Figure 3. 112-pin LQFP Pin Assignments

Figure 4 shows the pinout configuration for the 121 MAPBGA.

Table 3. Pin Functions by Primary and Alternate Purpose

Pin Group	Primary Function	SecondaryFunction	Tertiary Function	Quaternary Function	Drive Strength/ Control[1]	Wired OR Control	Pull-up/ Pull-down[2]	Pin on 121 MAPBGA	Pin on 112 LQFP	Pin on 80 LQFP
ADC[3]	AN7	—	—	PAN[7]	Low	—	—	A10	88	64
	AN6	—	—	PAN[6]	Low	—	—	B10	87	63
	AN5	—	—	PAN[5]	Low	—	—	A11	86	62
	AN4	—	—	PAN[4]	Low	—	—	B11	85	61
	AN3	—	—	PAN[3]	Low	—	—	C9	89	65
	AN2	—	—	PAN[2]	Low	—	—	B9	90	66
	AN1	—	—	PAN[1]	Low	—	—	A9	91	67
	AN0	—	—	PAN[0]	Low	—	—	C8	92	68
	SYNCA	CANTX[4]	FEC_MDIO	PAS[3]	PDSR[39]	—	—	K1	28	20
	SYNCB	CANRX[4]	FEC_MDC	PAS[2]	PDSR[39]	—	—	J1	27	19
	VDDA	—	—	—	N/A	N/A	—	A8	93	69
	VSSA	—	—	—	N/A	N/A	—	A7	96	72
	VRH	—	—	—	N/A	N/A	—	B8	94	70
	VRL	—	—	—	N/A	N/A	—	B7	95	71
Clock Generation	EXTAL	—	—	—	N/A	N/A	—	L7	48	36
	XTAL	—	—	—	N/A	N/A	—	J7	49	37
	VDDPLL[5]	—	—	—	N/A	N/A	—	K6	45	33
	VSSPLL	—	—	—	N/A	N/A	—	K7	47	35
Debug Data	ALLPST	—	—	—	High	—	—	D3	7	7
	DDATA[3:0]	—	—	PDD[7:4]	High	—	—	E1, F3,F2, F1	12,13,16,17	—
	PST[3:0]	—	—	PDD[3:0]	High	—	—	D10, D9, E10, E9	80,79,78,77	—

Table 3. Pin Functions by Primary and Alternate Purpose (continued)

Pin Group	Primary Function	SecondaryFunction	Tertiary Function	Quaternary Function	Drive Strength/ Control[1]	Wired OR Control	Pull-up/ Pull-down[2]	Pin on 121 MAPBGA	Pin on 112 LQFP	Pin on 80 LQFP
QSPI[3]	QSPI_DIN/ EZPD	CANRX[4]	URXD1	PQS[1]	PDSR[2]	PWOR[4]	—	H4	34	25
	QSPI_DOUT/EZPQ	CANTX[4]	UTXD1	PQS[0]	PDSR[1]	PWOR[5]	—	J4	35	26
	QSPI_CLK/ EZPCK	SCL	URTS1	PQS[2]	PDSR[3]	PWOR[6]	Pull-Up[8]	K4	36	27
	QSPI_CS3	SYNCA	SYNCB	PQS[6]	PDSR[7]	—	—	K5	40	—
	QSPI_CS2	—	FEC_TXCLK	PQS[5]	PDSR[6]	—	—	J5	39	—
	QSPI_CS1	—	FEC_TXEN	PQS[4]	PDSR[5]	—	—	H5	38	—
	QSPI_CS0	SDA	UCTS1	PQS[3]	PDSR[4]	PWOR[7]	Pull-Up[8]	L4	37	28
Reset[9]	RSTI	—	—	—	N/A	N/A	Pull-Up[9]	J6	44	32
	RSTO	—	—	—	high	—	—	L6	46	34
Test	TEST	—	—	—	N/A	N/A	Pull-Down	H7	50	38
Timers, 16-bit[3]	GPT3	FEC_TXD[3]	PWM7	PTA[3]	PDSR[23]	—	Pull-Up[10]	B4	107	75
	GPT2	FEC_TXD[2]	PWM5	PTA[2]	PDSR[22]	—	Pull-Up[10]	C4	108	76
	GPT1	FEC_TXD[1]	PWM3	PTA[1]	PDSR[21]	—	Pull-Up[10]	D4	109	77
	GPT0	FEC_TXER	PWM1	PTA[0]	PDSR[20]	—	Pull-Up[10]	B3	110	78
Timers, 32-bit	DTIN3	DTOUT3	PWM6	PTC[3]	PDSR[19]	—	—	H1	22	14
	DTIN2	DTOUT2	PWM4	PTC[2]	PDSR[18]	—	—	G1	21	13
	DTIN1	DTOUT1	PWM2	PTC[1]	PDSR[17]	—	—	D1	9	9
	DTIN0	DTOUT0	PWM0	PTC[0]	PDSR[16]	—	—	D2	8	8
UART 0[3]	$\overline{\text{UCTS0}}$	CANRX[4]	FEC_RXCLK	PUA[3]	PDSR[11]	—	—	J2	26	18
	$\overline{\text{URTS0}}$	CANTX[4]	FEC_RXDV	PUA[2]	PDSR[10]	—	—	H2	25	17
	URXD0	—	FEC_RXD[0]	PUA[1]	PDSR[9]	PWOR[0]	—	K2	30	21
	UTXD0	—	FEC_CRS	PUA[0]	PDSR[8]	PWOR[1]	—	L2	31	22

Table 3. Pin Functions by Primary and Alternate Purpose (continued)

Pin Group	Primary Function	SecondaryFunction	Tertiary Function	Quaternary Function	Drive Strength/ Control[1]	Wired OR Control	Pull-up/ Pull-down[2]	Pin on 121 MAPBGA	Pin on 112 LQFP	Pin on 80 LQFP
UART 1[3]	$\overline{\text{UCTS1}}$	SYNCA	URXD2	PUB[3]	PDSR[15]	—	—	J3	24	16
	$\overline{\text{URTS1}}$	SYNCB	UTXD2	PUB[2]	PDSR[14]	—	—	H3	23	15
	URXD1	—	FEC_TXD[0]	PUB[1]	PDSR[13]	PWOR[2]	—	K3	32	23
	UTXD1	—	FEC_COL	PUB[0]	PDSR[12]	PWOR[3]	—	L3	33	24
UART 2	$\overline{\text{UCTS2}}$	—	—	PUC[3]	PDSR[27]	—	—	L10	61	—
	$\overline{\text{URTS2}}$	—	—	PUC[2]	PDSR[26]	—	—	K10	60	—
	URXD2	—	—	PUC[1]	PDSR[25]	—	—	K11	62	—
	UTXD2	—	—	PUC[0]	PDSR[24]	—	—	L11	63	—
FlexCAN	SYNCA	CANTX[4]	FEC_MDIO	PAS[3]	PDSR[39]	—	—	—	28	20
	SYNCB	CANRX[4]	FEC_MDC	PAS[2]	PDSR[39]	—	—	—	27	19
VDD[5,11]	VDD	—	—	—	N/A	N/A	—	D7, E8	65,102	45,74
VDDX	VDDX	—	—	—	N/A	N/A	—	D5, D6, E6, G5, G6, G7, H6	14, 43	10, 31
VSS	VSS	—	—	—	N/A	N/A	—	E4, E5, E7,F4, F5, F6, F7, F8	64,101	44,73
VSSX	VSSX	—	—	—	N/A	N/A	—	—	15, 42	11, 30

1 The PDSR and PSSR registers are described in Chapter 14, "General Purpose I/O Module. All programmable signals default to 2mA drive in normal (single-chip) mode.
2 All signals have a pull-up in GPIO mode.
3 The use of an external PHY limits ADC, interrupt, and QSPI functionality. It also disables the UART0/1 and timer pins.
4 The multiplexed CANTX and CANRX signals do not have dedicated pins, but are available as muxed replacements for other signals.
5 The VDD1, VDD2, VDDPLL, and PHY_VDD pins are for decoupling only and should not have power directly applied to them.
6 For primary and GPIO functions only.
7 Only when JTAG mode is enabled.
8 For secondary and GPIO functions only.
9 RSTI has an internal pull-up resistor; however, the use of an external resistor is strongly recommended.
10 For GPIO function. Primary Function has pull-up control within the GPT module.
11 This list for power and ground does not include those dedicated power/ground pins included elsewhere, e.g. in the Ethernet PHY.

1.7 Queued Serial Peripheral Interface (QSPI)

Table 8 describes QSPI signals.

Table 8. Queued Serial Peripheral Interface (QSPI) Signals

Signal Name	Abbreviation	Function	I/O
QSPI Synchronous Serial Output	QSPI_DOUT	Provides the serial data from the QSPI and can be programmed to be driven on the rising or falling edge of QSPI_CLK.	O
QSPI Synchronous Serial Data Input	QSPI_DIN	Provides the serial data to the QSPI and can be programmed to be sampled on the rising or falling edge of QSPI_CLK.	I
QSPI Serial Clock	QSPI_CLK	Provides the serial clock from the QSPI. The polarity and phase of QSPI_CLK are programmable.	O
Synchronous Peripheral Chip Selects	QSPI_CS[3:0]	QSPI peripheral chip selects that can be programmed to be active high or low.	O

1.8 Fast Ethernet Controller EPHY Signals

Table 9 describes the Fast Ethernet Controller (FEC) signals.

Table 9. Fast Ethernet Controller (FEC) Signals

Signal Name	Abbreviation	Function	I/O
Twisted Pair Input +	RXP	Differential Ethernet twisted-pair input pin. This pin is high-impedance out of reset.	I
Twisted Pair Input -	RXN	Differential Ethernet twisted-pair input pin. This pin is high-impedance out of reset.	I
Twisted Pair Output +	TXN	Differential Ethernet twisted-pair output pin. This pin is high-impedance out of reset.	O
Twisted Pair Output -	TXP	Differential Ethernet twisted-pair output pin. This pin is high-impedance out of reset.	O
Bias Control Resistor	RBIAS	Connect a 12.4 kΩ (1.0%) external resistor, RBIAS, between the PHY_RBIAS pin and analog ground. Place this resistor as near to the chip pin as possible. Stray capacitance must be kept to less than 10 pF (>50 pF causes instability). No high-speed signals can be permitted in the region of RBIAS.	I
Activity LED	ACT_LED	Indicates when the EPHY is transmitting or receiving	O
Link LED	LINK_LED	Indicates when the EPHY has a valid link	O
Speed LED	SPD_LED	Indicates the speed of the EPHY connection	O
Duplex LED	DUPLED	Indicates the duplex (full or half) of the EPHY connection	O
Collision LED	COLLED	Indicates if the EPHY detects a collision	O
Transmit LED	TXLED	Indicates if the EPHY is transmitting	O
Receive LED	RXLED	Indicates if the EPHY is receiving	O

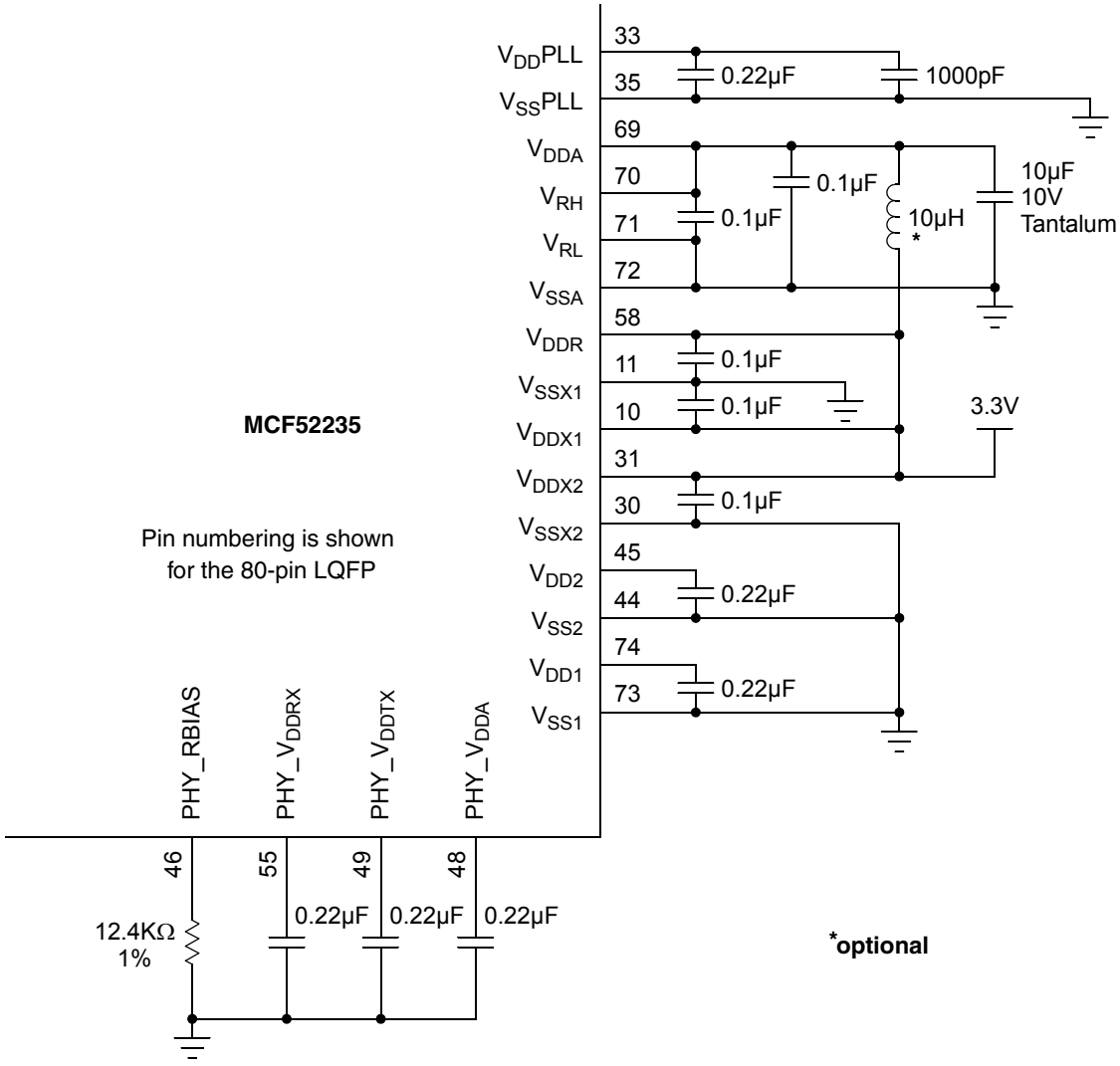


Figure 5. Suggested Connection Scheme for Power and Ground

2 Electrical Characteristics

This section contains electrical specification tables and reference timing diagrams for the MCF52235, including detailed information on power considerations, DC/AC electrical characteristics, and AC timing specifications.

NOTE

The parameters specified in this appendix supersede any values found in the module specifications.

The average chip-junction temperature (T_J) in °C can be obtained from

$$T_J = T_A + (P_D \times \Theta_{JMA}) \quad \textit{Eqn. 1}$$

where

- T_A = ambient temperature, °C
- Θ_{JMA} = package thermal resistance, junction-to-ambient, °C/W
- $P_D = P_{INT} + P_{I/O}$
- P_{INT} = chip internal power, $I_{DD} \times V_{DD}$, watts
- $P_{I/O}$ = power dissipation on input and output pins — user determined

For most applications, PI/O < P_{INT} and can be ignored. An approximate relationship between P_D and T_J (if $P_{I/O}$ is neglected) is:

$$P_D = K \div (T_J + 273°C) \quad \textit{Eqn. 2}$$

Solving equations 1 and 2 for K gives:

$$K = P_D \times (T_A + 273°C) + \Theta_{JMA} \times P_D^2 \quad \textit{Eqn. 3}$$

where K is a constant pertaining to the particular part. K can be determined from Equation 3 by measuring P_D (at equilibrium) for a known T_A. Using this value of K, the values of P_D and T_J can be obtained by solving Equation 1 and Equation 2 iteratively for any value of T_A.

2.2 ESD Protection

Table 21. ESD Protection Characteristics[1]

Characteristic	Symbol	Value	Units
ESD target for Human Body Model	HBM	1500 (ADC and EPHY pins) 2000 (All other pins)	V
ESD target for Charged Device Model	CDM	250	V
HBM circuit description	R_{series}	1500	ohms
	C	100	pF
Number of pulses per pin (HBM) positive pulses negative pulses	 — —	 1 1	—
Number of pulses per pin (CDM) positive pulses negative pulses	 — —	 3 3	—
Interval of pulses (HBM)	—	1.0	sec
Interval of pulses (CDM)	—	0.2	sec

[1] A device is defined as a failure if the device no longer meets the device specification requirements after exposure to ESD pulses. Complete DC parametric and functional testing is performed per applicable device specification at room temperature followed by hot temperature, unless specified otherwise in the device specification.

Table 23. Active Current Consumption Specifications

Characteristic	Symbol	Typical				Peak	Unit
		Running from SRAM, EPHY Off	Running from Flash, EPHY Off	Running from Flash, EPHY 10BaseT	Running from Flash, EPHY 100BaseT		
Active current, core and I/O PLL @25 MHz PLL @60 MHz	$I_{DDR}+I_{DDX}+I_{DDA}$	 75 130	 82 138	 150 220	 260 310	 290 340	 mA
Analog supply current Normal operation Low-power STOP	I_{DDA}	 20 15	 20 15	 20 15	 20 15	 30 50	 mA μA

Table 24. Current Consumption Specifications in Low-Power Modes[1]

Mode[2]	PLL @25 MHz (typical)[3]	PLL @60 MHz (typical)[3]	PLL @60 MHz (peak)[4]	Unit
STOP mode 3 (STPMD[1:0]=11)	0.2		1.0	mA
STOP mode 2 (STPMD[1:0]=10)	7		—	
STOP mode 1 (STPMD[1:0]=01)	10	12	—	
STOP mode 0 (STPMD[1:0]=00)	10	12	—	
WAIT	16	27	—	
DOZE	16	27	—	
RUN	25	45	—	

1 All values are measured with a 3.30 V power supply.

2 Refer to the “Power Management” chapter in the *MCF52235 ColdFire® Integrated Microcontroller Reference Manual* for more information on low-power modes.

3 These values were obtained with CLKOUT and all peripheral clocks except for the CFM clock disabled prior to entering low-power mode. The tests were performed at room temperature. All code was executed from flash memory; running code from SRAM further reduces power consumption.

4 These values were obtained with CLKOUT and all peripheral clocks enabled. All code was executed from flash memory.

2.6 Reset Timing

Table 27. Reset and Configuration Override Timing

(V_{DD} = 2.7 to 3.6 V, V_{SS} = 0 V, T_A = T_L to T_H)[1]

Num	Characteristic	Symbol	Min	Max	Unit
R1	$\overline{\text{RSTI}}$ input valid to CLKOUT high	t_{RVCH}	9	—	ns
R2	CLKOUT high to $\overline{\text{RSTI}}$ input invalid	t_{CHRI}	1.5	—	ns
R3	$\overline{\text{RSTI}}$ input valid time [2]	t_{RIVT}	5	—	t_{CYC}
R4	CLKOUT high to $\overline{\text{RSTO}}$ valid	t_{CHROV}	—	10	ns

1 All AC timing is shown with respect to 50% V_{DD} levels unless otherwise noted.

2 During low power STOP, the synchronizers for the $\overline{\text{RSTI}}$ input are bypassed and $\overline{\text{RSTI}}$ is asserted asynchronously to the system. Therefore, $\overline{\text{RSTI}}$ must be held a minimum of 100ns.

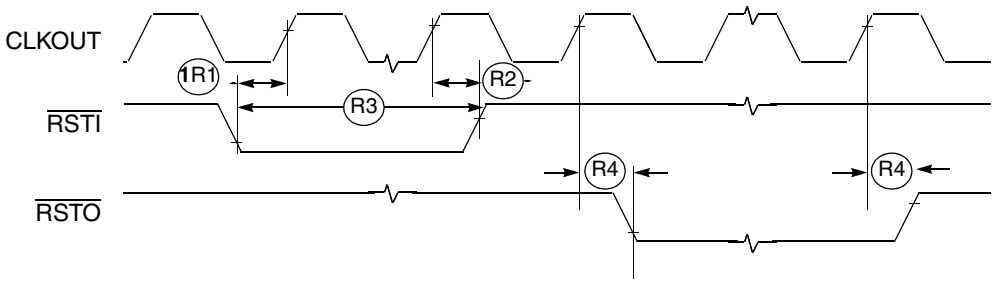


Figure 7. $\overline{\text{RSTI}}$ and Configuration Override Timing

2.7 I²C Input/Output Timing Specifications

Table 28 lists specifications for the I²C input timing parameters shown in Figure 8.

Table 28. I²C Input Timing Specifications between I2C_SCL and I2C_SDA

Num	Characteristic	Min	Max	Units
I1	Start condition hold time	2 × t_{CYC}	—	ns
I2	Clock low period	8 × t_{CYC}	—	ns
I3	SCL/SDA rise time (V_{IL} = 0.5 V to V_{IH} = 2.4 V)	—	1	ms
I4	Data hold time	0	—	ns
I5	SCL/SDA fall time (V_{IH} = 2.4 V to V_{IL} = 0.5 V)	—	1	ms
I6	Clock high time	4 × t_{CYC}	—	ns
I7	Data setup time	0	—	ns
I8	Start condition setup time (for repeated start condition only)	2 × t_{CYC}	—	ns
I9	Stop condition setup time	2 × t_{CYC}	—	ns

Table 29 lists specifications for the I²C output timing parameters shown in Figure 8.

2.13 JTAG and Boundary Scan Timing

Table 39. JTAG and Boundary Scan Timing

Num	Characteristics[1]	Symbol	Min	Max	Unit
J1	TCLK frequency of operation	f_{JCYC}	DC	1/4	$f_{sys/2}$
J2	TCLK cycle period	t_{JCYC}	$4 \times t_{CYC}$	—	ns
J3	TCLK clock pulse width	t_{JCW}	26	—	ns
J4	TCLK rise and fall times	t_{JCRF}	0	3	ns
J5	Boundary scan input data setup time to TCLK rise	t_{BSDST}	4	—	ns
J6	Boundary scan input data hold time after TCLK rise	t_{BSDHT}	26	—	ns
J7	TCLK low to boundary scan output data valid	t_{BSDV}	0	33	ns
J8	TCLK low to boundary scan output high Z	t_{BSDZ}	0	33	ns
J9	TMS, TDI input data setup time to TCLK rise	t_{TAPBST}	4	—	ns
J10	TMS, TDI input data hold time after TCLK rise	t_{TAPBHT}	10	—	ns
J11	TCLK low to TDO data valid	t_{TDODV}	0	26	ns
J12	TCLK low to TDO high Z	t_{TDODZ}	0	8	ns
J13	$\overline{TRST}$ assert time	t_{TRSTAT}	100	—	ns
J14	$\overline{TRST}$ setup time (negation) to TCLK high	t_{TRSTST}	10	—	ns

1 JTAG_EN is expected to be a static signal. Hence, it is not associated with any timing.

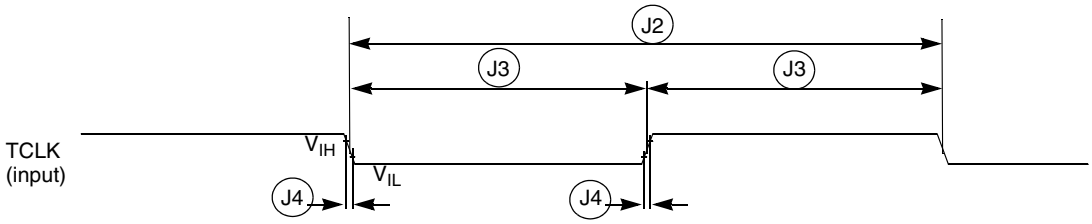


Figure 14. Test Clock Input Timing

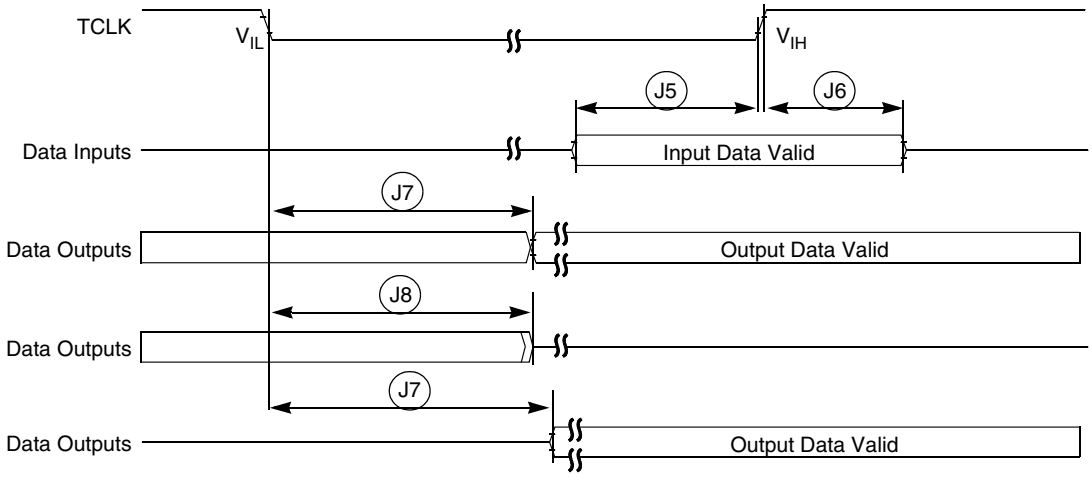


Figure 15. Boundary Scan (JTAG) Timing

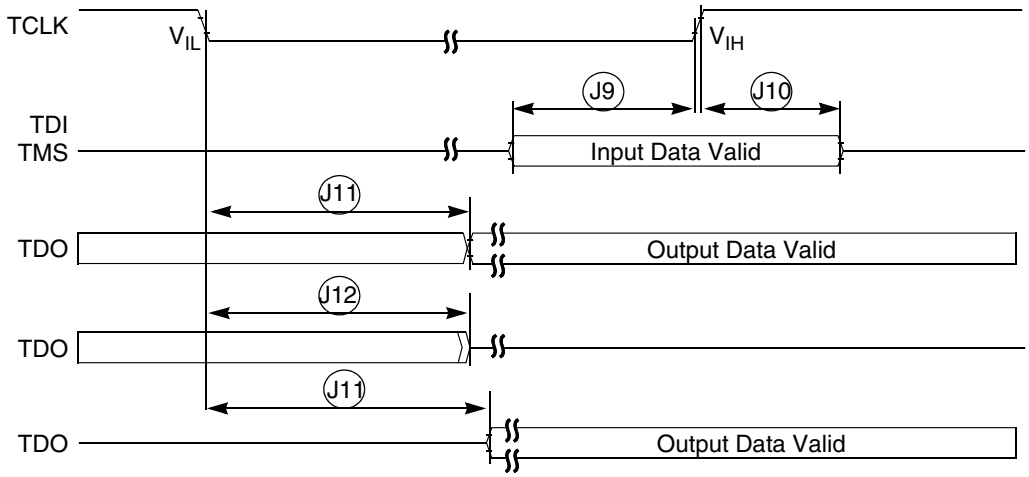


Figure 16. Test Access Port Timing

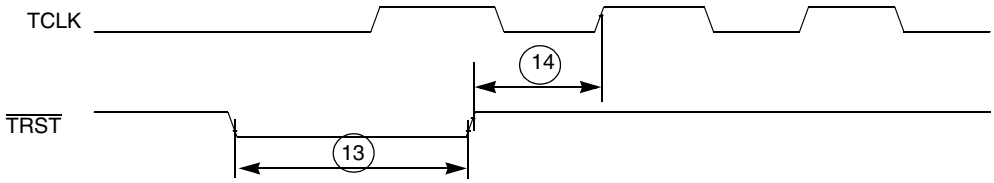
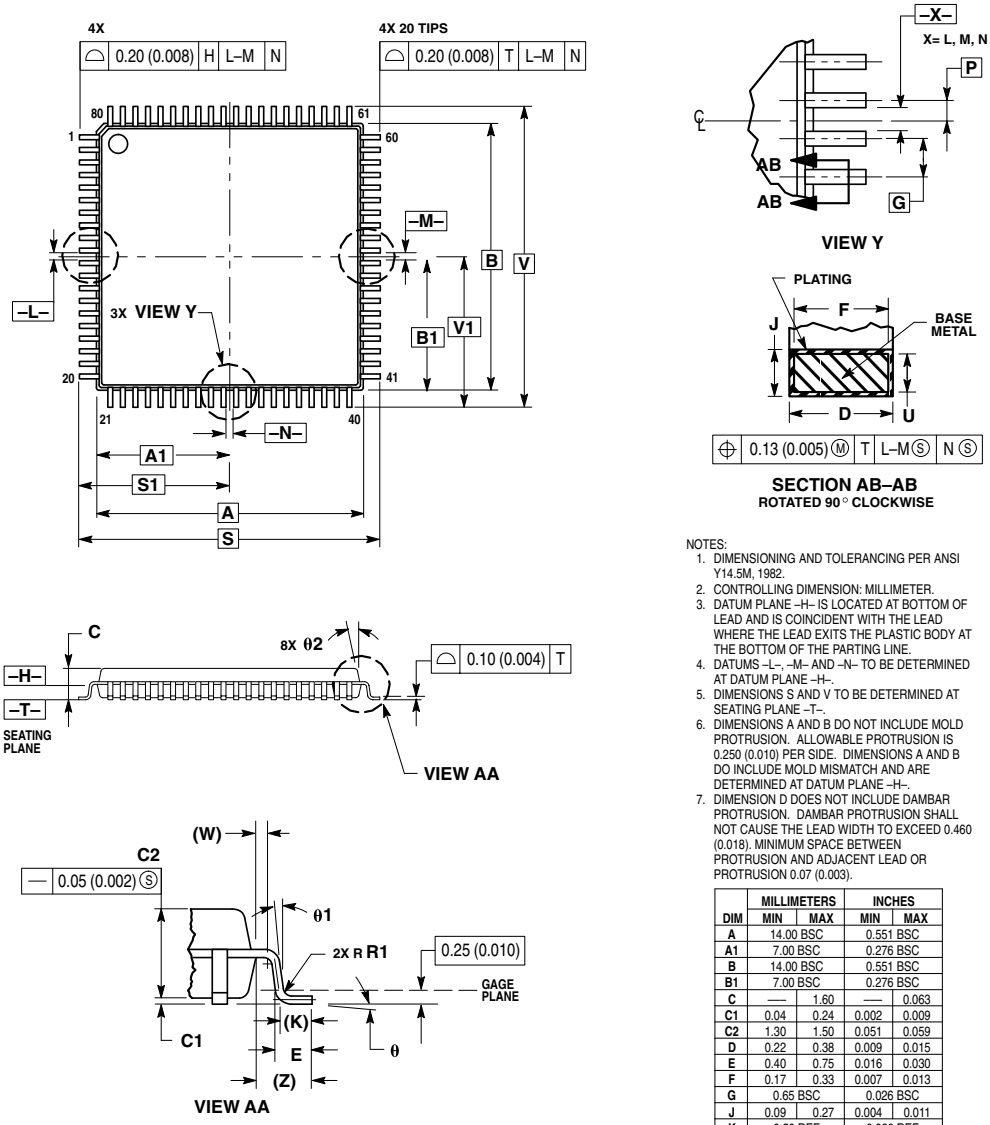


Figure 17. TRST Timing

3 Mechanical Outline Drawings

This section describes the physical properties of the MCF52235 and its derivatives.

3.1 80-pin LQFP Package



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE –H– IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS –L–, –M– AND –N– TO BE DETERMINED AT DATUM PLANE –H–.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE –T–.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE –H–.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.460 (0.018). MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 (0.003).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	14.00 BSC		0.551 BSC	
A1	7.00 BSC		0.276 BSC	
B	14.00 BSC		0.551 BSC	
B1	7.00 BSC		0.276 BSC	
C	—	1.60	—	0.063
C1	0.04	0.24	0.002	0.009
C2	1.30	1.50	0.051	0.059
D	0.22	0.38	0.009	0.015
E	0.40	0.75	0.016	0.030
F	0.17	0.33	0.007	0.013
G	0.65 BSC		0.026 BSC	
J	0.09	0.27	0.004	0.011
K	0.50 REF		0.020 REF	
P	0.325 BSC		0.013 REF	
R1	0.10	0.20	0.004	0.008
S	16.00 BSC		0.630 BSC	
S1	8.00 BSC		0.315 BSC	
U	0.09	0.16	0.004	0.006
V	16.00 BSC		0.630 BSC	
V1	8.00 BSC		0.315 BSC	
W	0.20 REF		0.008 REF	
Z	1.00 REF		0.039 REF	
θ	0°	10°	0°	10°
θ1	0°	—	0°	—
θ2	9°	14°	9°	14°

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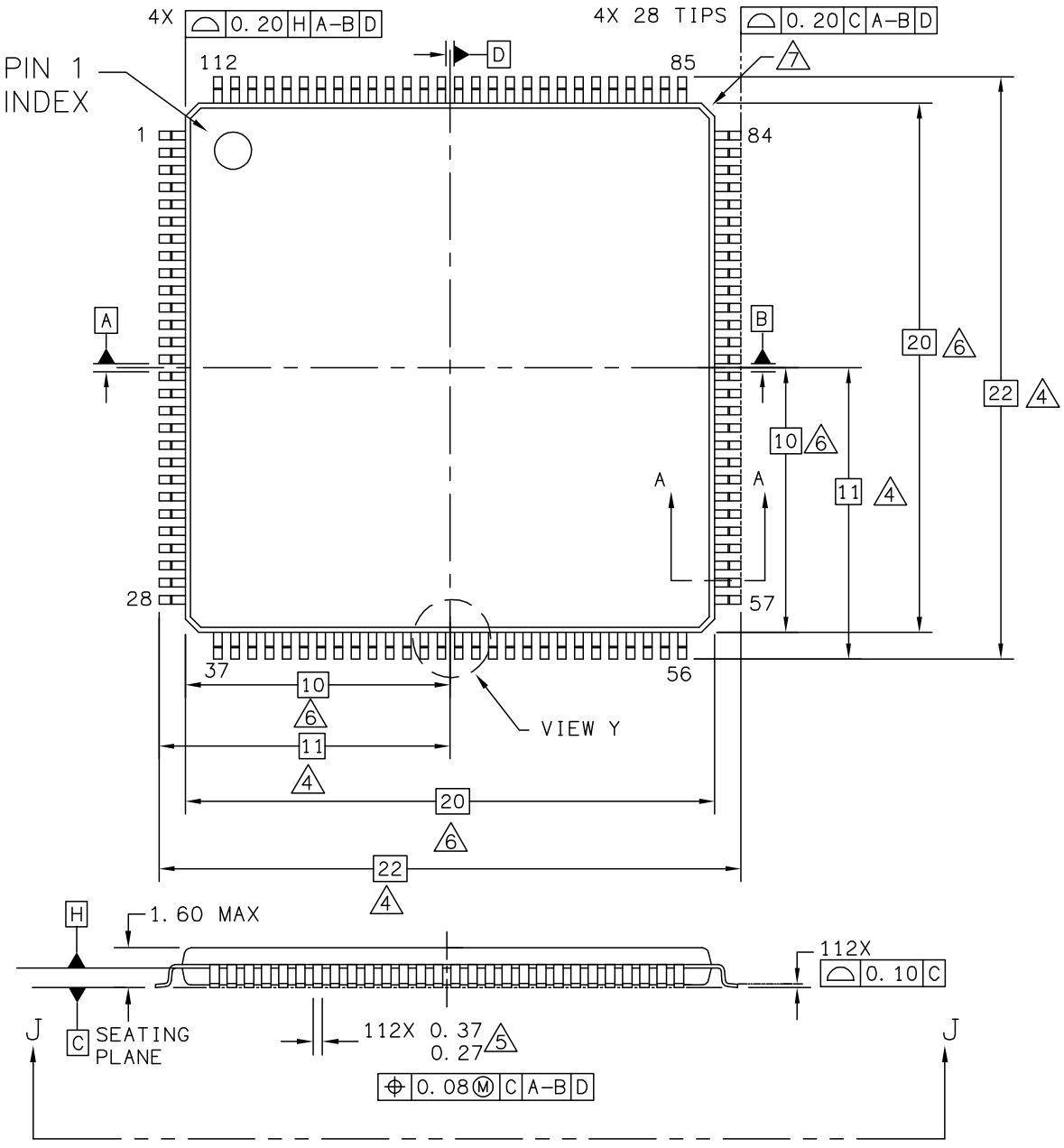
ISSUE C

DATE 09/21/95

3.2 112-pin LQFP Package



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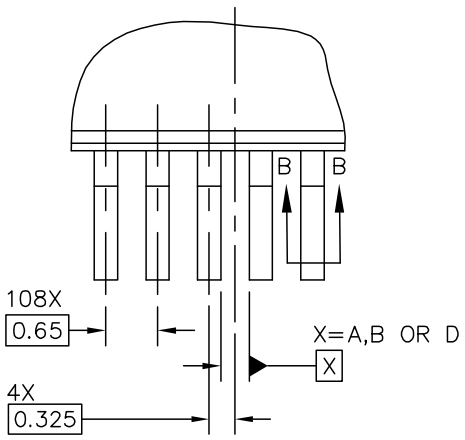
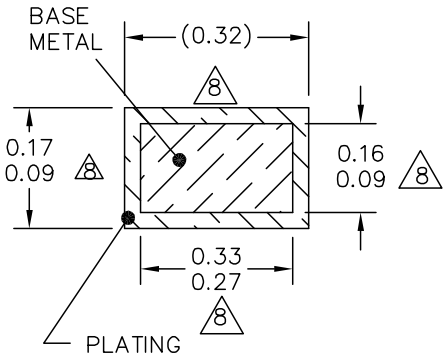
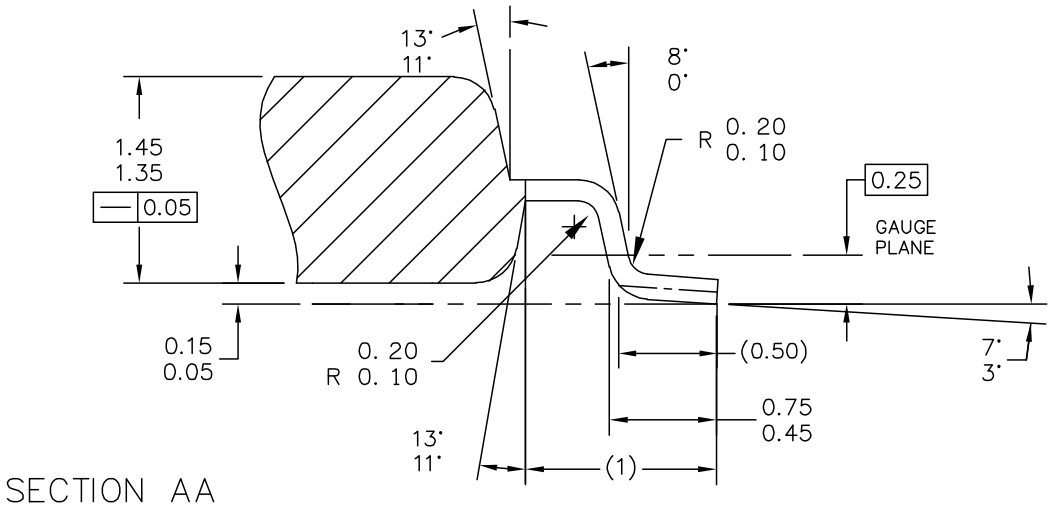
TITLE: 112LD LQFP 20 X 20 X 1.4 0.65 PITCH	DOCUMENT NO: 98ASS23330W	REV: E
	CASE NUMBER: 987-02	25 MAY 2005
	STANDARD: JEDEC MS-026 BFA	



VIEW Y



SECTION B–B



SECTION AA

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TITLE: 112LD LQFP 20 X 20 X 1.4 0.65 PITCH	DOCUMENT NO: 98ASS23330W	REV: E
	CASE NUMBER: 987–02	25 MAY 2005
	STANDARD: JEDEC MS–026 BFA	

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.
5. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08 MM. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 MM.
6. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.254 MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 MM AND 0.25 MM FROM THE LEAD TIP.

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE: 112LD LQFP, 20 X 20 X 1.4 PKG, 0.65 PITCH	DOCUMENT NO: 98ASS23330W	REV: E
	CASE NUMBER: 987–02	25 MAY 2005
	STANDARD: JEDEC MS–026 BFA	

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: PBGA, LOW PROFILE, 121 I/O, 12 X 12 PKG, 1 MM PITCH (MAP)	DOCUMENT NO: 98ARE10645D	REV: O
	CASE NUMBER: 1817–01	15 NOV 2005
	STANDARD: NON–JEDEC	